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## UNITED STATES PATENT DOCUMENTS

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## FOREIGN PATENT DOCUMENTS

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lm	AA	WO 01/24239 A1	04/05/01	International			

## OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

lm	BA	Cerisier et al., "Growth Mode of Copper Films Electrodeposited on Silicon from Sulfate and Pyrophosphate Solutions", Journal of The Electrochemical Society, 146 (6) 2156-2162 (1999).
	BB	Hosoi et al., "Two-step Copper Electroplating Technique Using Seed Enhancement Step with Alkali-Metal-Free Copper Pyrophosphate Bath", IITC pp. 277-279, 2001.
	BC	Long et al., "Deposition of Copper on TIN From Pyrophosphate Solution", Electrochemical Society Proceedings Volume 99-9, pp 149-155, 1999.
↓	BD	Radisic et al., "Nucleation and Growth of Copper on TiN from Pyrophosphate Solution", Journal of The Electrochemical Society, 148 (1) C41-C46 (2001).

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